Features

Air Bubbles Free Mounting

Minimal Contact with Wafer

Vacuum Mount, No Roller

UV Tape Capability

High Accuracy in X-Y & Theta Rotation

Vacuum Mounting -- This advanced method gives you the following benefits:

Wafer/tape is mounted inside a vacuum chamber. Nothing touches wafer except tape and edge support.

No roller required. No more difficult alignment of roller/wafer parallelism, roller cleaning, and no pressure variation on wafer due to different thickness.

Absolutely no air bubble and better adhesion.

Tape tension is controlled and programmable.

Quick change wafer chuck.